

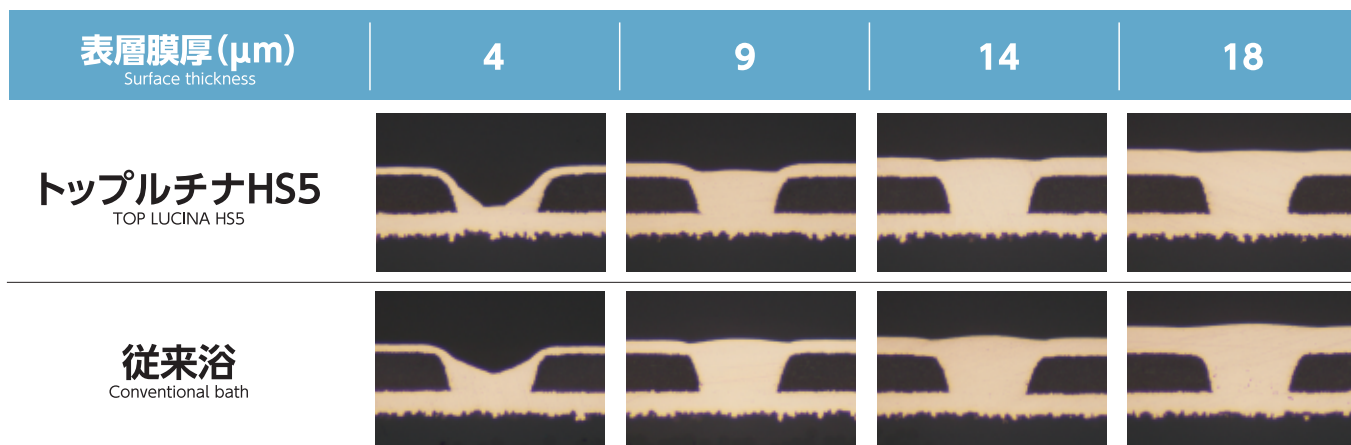
トッパールチナHS5

TOP LUCINA HS5

- オーバーフィリング時も凸形状になりにくく、スタックビア形成に最適
Inhibit convex shape formation by over-filling, best for stacked vias
- 膜厚均一性に優れ、設計通りの回路形成が可能
Excellent in thickness uniformity, can freely design ideal patterns
- 矩形性に優れ、高周波高速伝送に対応
Square-shape patterns can be obtained, suitable for high-frequency, high-speed transmission

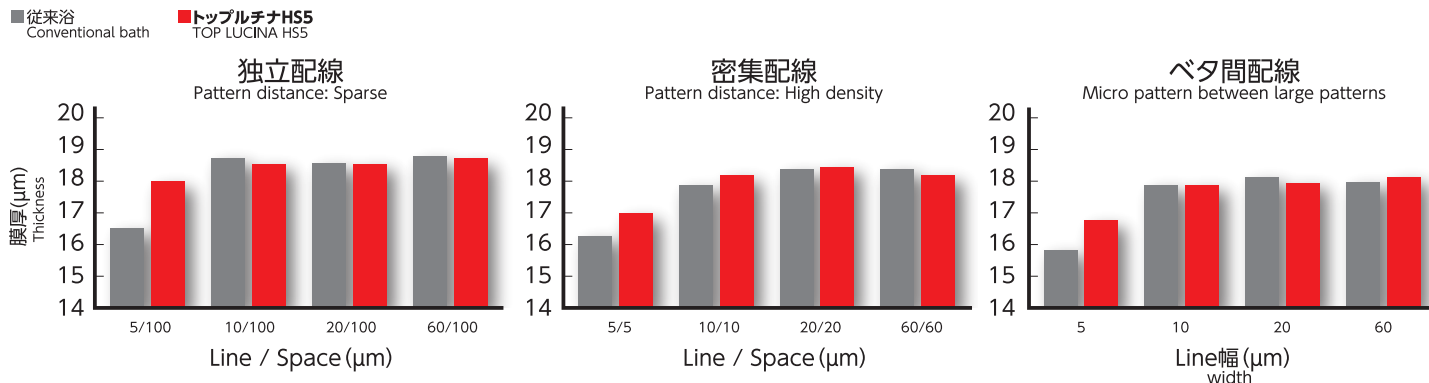
短時間でフィリングが完了し、かつ凸形状になりにくい

Can finish filling in a short time, inhibit convex shape formation



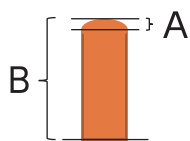
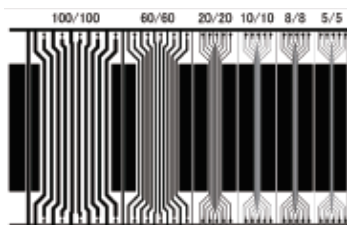
配線幅間の膜厚のばらつきが小さい

Small thickness variation between patterns



良好な矩形性

Square-shape patterns can be obtained



矩形性 = $(A/B) \times 100(\%)$
Square-shape ratio

